

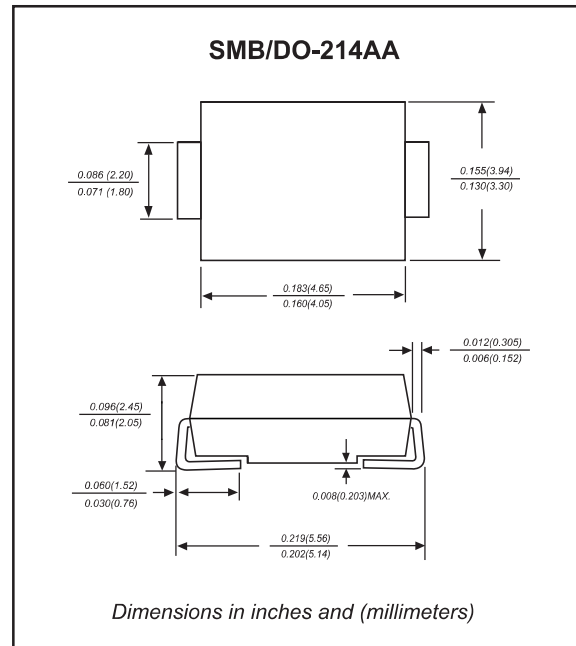
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free

Mechanical data

- ◆ **Case:** JEDEC DO-214AA molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS		Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1		I _O			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)		I _{FSM}			50	A
Reverse current	T _A = 25°C	V _R = 20V - 60V	I _R			0.5	mA
		V _R = 80V - 200V				0.1	
Reverse current	T _A = 100°C	V _R = 20V - 60V	I _R			10	mA
		V _R = 80V - 200V				5	
Thermal resistance	Junction to ambient NOTE 1		R _{θJA}		75		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage		C _J		220		pF
Storage temperature			T _{STG}	-65		+150	°C

Note: 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

SYMBOLS	V _{RM} *1 (V)	V _{RMS} *2 (V)	V _R *3 (V)	V _F *4 (V)	Operating temperature T _J , (°C)
SS22-B	20	14	20	0.55	-55 to +125
SS23-B	30	21	30		
SS24-B	40	28	40		
SS25-B	50	35	50	0.70	-55 to +150
SS26-B	60	42	60		
SS28-B	80	56	80	0.85	
SS210-B	100	70	100		
SS215-B	150	105	150	0.92	
SS220-B	200	140	200		

*1 Repetitive peak reverse voltage

*2 RMS voltage

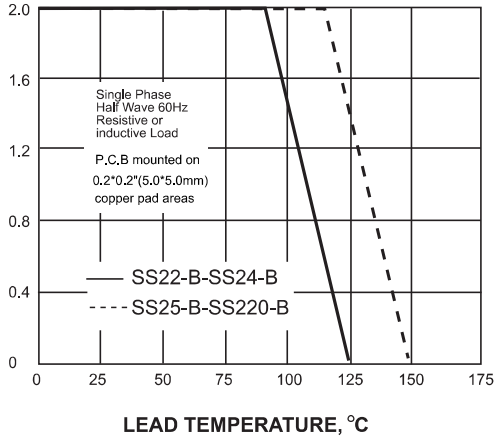
*3 Continuous reverse voltage

*4 Maximum forward voltage@I_F=2.0A

Rating and characteristic curves

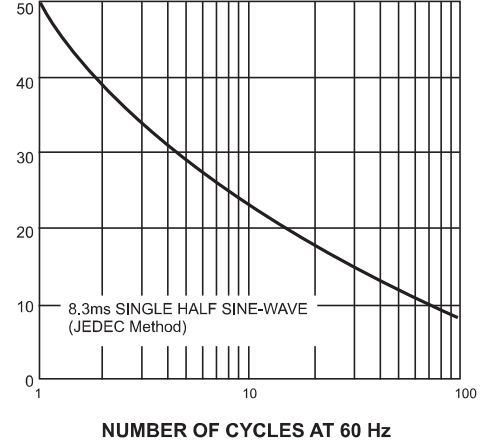
AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



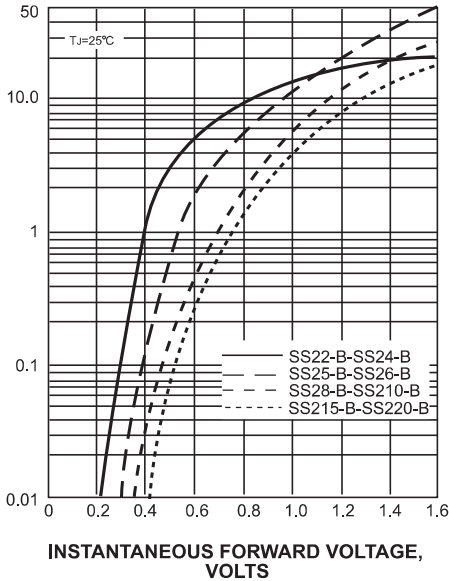
PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



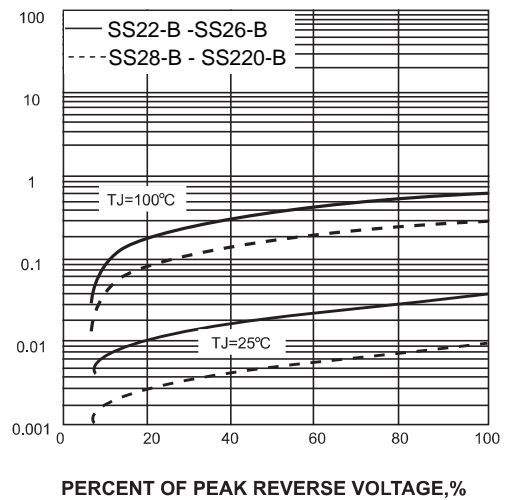
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



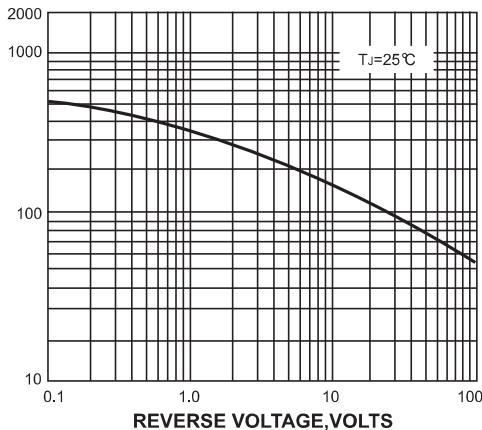
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



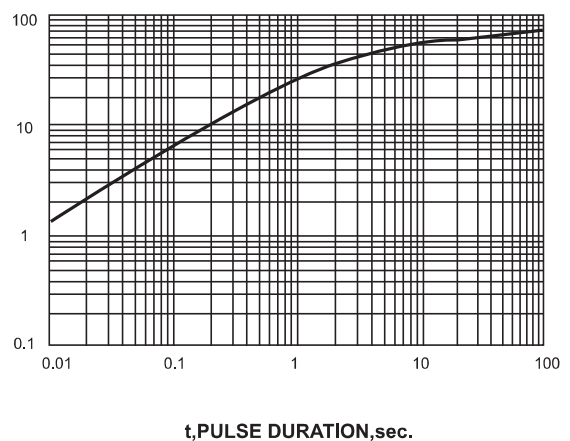
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE





TRANSIENT THERMAL IMPEDANCE, °C/W

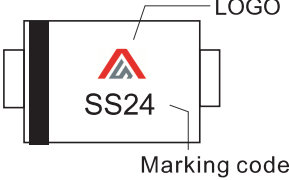
FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



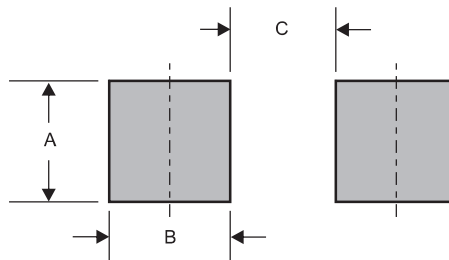
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
SS22-B	SS22	
SS23-B	SS23	
SS24-B	SS24	
SS25-B	SS25	
SS26-B	SS26	
SS28-B	SS28	
SS210-B	SS210	
SS215-B	SS215	
SS220-B	SS220	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.090(2.30)	0.098(2.50)	0.070(1.80)